

| | Type | Hits | Search Text | DBs |
|---|------|------|--|------------|
| 1 | BRS | 71 | ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and grid adj array and multi\$3 near (contact or terminal or pad) | USPAT; JPO |
| 2 | BRS | 344 | ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and multi\$3 near (contact or terminal or pad) | USPAT; JPO |
| 3 | BRS | 51 | ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and ((multi\$3 near layers) near (contact or terminal or pad)) | USPAT; JPO |
| 4 | BRS | 6 | ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and ((multi\$3 near layers) near (bump)) | USPAT; JPO |
| 5 | BRS | 0 | ("chip on chip" or stack\$3 near (chip or die or IC or semiconductor)) and ((multi\$3 near layers) near (bump)) | USPAT; JPO |
| 6 | BRS | 4 | ("chip on chip" or stack\$3 near (chip or die or IC or semiconductor)) and layers near (bump) | USPAT; JPO |
| 7 | BRS | 6 | ("chip on chip" or stack\$3 near (chip or die or IC or semiconductor)) and (layers or coat\$3) near (bump) | USPAT; JPO |
| 8 | BRS | 157 | ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and multi\$3 near (contact or terminal or pad) | USPAT |

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|----|------|------|--|------------|
| 9 | BRS | 344 | ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and multi\$3 near (contact or terminal or pad) | USPAT; JPO |
| 10 | BRS | 23 | ("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and coat\$3 near (contact or terminal or pad) | USPAT; JPO |
| 11 | BRS | 17 | ("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and coat\$3 near (contact or terminal or bump) | USPAT; JPO |
| 12 | BRS | 12 | "4032058" | USPAT; JPO |
| 13 | BRS | 46 | ("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and (coat\$3 or cover) near (contact or terminal or bump or ball) | USPAT; JPO |
| 14 | BRS | 46 | ("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and (coat\$3 or cover) near (contact or terminal or bump or ball) | USPAT; JPO |
| 15 | BRS | 396 | ("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and (coat\$3 or cover or layers) near (contact or terminal or bump or ball) | USPAT; JPO |
| 16 | BRS | 46 | ("chip on chip" or (stack\$3 near (chip or die or IC or semiconductor))) and (coat\$3 or cover) near (contact or terminal or bump or ball) | USPAT; JPO |
| 17 | BRS | 1 | "3392442".PN. | USPAT |
| 18 | BRS | 1 | "3436818".PN. | USPAT |
| 19 | BRS | 1 | "3486223".PN. | USPAT |
| 20 | BRS | 1 | "4617730".PN. | USPAT |

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|----|------|------|---|------------|
| 21 | BRS | 1 | "5007163".PN. | USPAT |
| 22 | BRS | 1 | "5075965".PN. | USPAT |
| 23 | BRS | 1 | "5203075".PN. | USPAT |
| 24 | BRS | 47 | "5007163" | USPAT; JPO |
| 25 | BRS | 46 | "5075965" | USPAT; JPO |
| 26 | BRS | 28 | "5075965" and (tin or Sn) | USPAT; JPO |
| 27 | BRS | 1 | "6268739" and (tin or Sn) | USPAT; JPO |
| 28 | BRS | 2 | "6166556" and (tin or Sn) | USPAT; JPO |
| 29 | BRS | 1166 | 257/777 and (contact or terminal or bump or ball or pad) | USPAT; JPO |
| 30 | BRS | 204 | 257/777 and (layers or films or coat\$3 or cover or cap) near (contact or terminal or bump or ball or pad) | USPAT; JPO |
| 31 | BRS | 65 | 257/777 and (layers or films or coat\$3 or cover or cap) near (contact or terminal or bump or ball or pad) and (tin or "Sn") | USPAT; JPO |
| 32 | BRS | 23 | "4369458" | USPAT; JPO |
| 33 | BRS | 19 | "5461261" | USPAT; JPO |
| 34 | BRS | 24 | "5796591" | USPAT; JPO |
| 35 | BRS | 136 | copper near melting adj point | USPAT; JPO |
| 36 | BRS | 13 | pure adj copper near melting adj point | USPAT; JPO |
| 37 | BRS | 59 | ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad) | JPO |

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| 38 | BRS | 8 | 04088645.pn. or 6137184.pn. or 6133637.pn. or 6268739.pn. or 6166556.pn. or 6337522.pn. or 5796591.pn. or 5646828.pn. | USPAT; JPO |
| 39 | BRS | 8 | 04088645.pn. or 6137184.pn. or 6133637.pn. or 6268739.pn. or 6166556.pn. or 6337522.pn. or 5796591.pn. or 5646828.pn. | USPAT; JPO |
| 40 | BRS | 337 | (257/777 or 361/760 or 438/108 or 438/109) and ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad or ball or bump) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 41 | BRS | 319 | (257/778 or 257/779 or 257/780 or 257/781) and ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad or ball or bump) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 42 | BRS | 260 | (257/723 or 257/724 or 257/685 or 257/686) and ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad or ball or bump) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |
| 43 | BRS | 208 | (257/690 or 257/700) and ("chip on chip" or stack\$3 or mount\$3) near (chip or die or IC or semiconductor) and (coat\$3 or cover or cap\$4 or layers) near (contact or terminal or pad or ball or bump) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB |